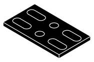
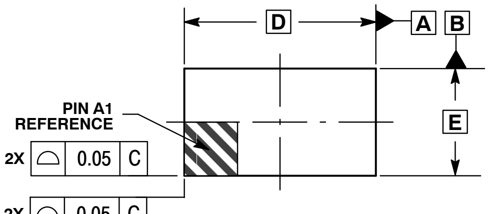
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS



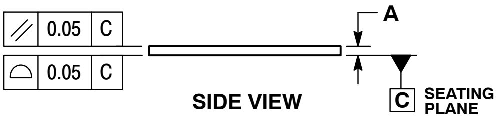
SCALE 4:1

WLCSP6, 2.11x1.18x0.10
CASE 567NP
ISSUE B

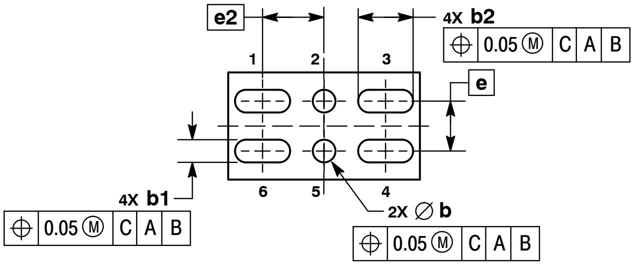
DATE 22 DEC 2016



TOP VIEW



SIDE VIEW



BOTTOM VIEW

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.

	MILLIMETERS		
DIM	MIN	NOM	MAX
A	0.08	0.10	0.12
b	0.22	0.25	0.28
b1	0.27	0.30	0.33
b2	0.575	0.605	0.635
D		2.11 BSC	
E		1.18 BSC	
e		0.55 BSC	
e2		0.6775 BSC	

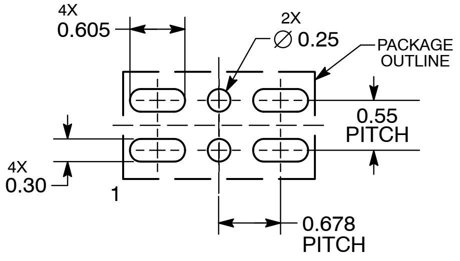
GENERIC MARKING DIAGRAM*

A = Assembly Location
Y = Year
W = Work Week
ZZ = Assembly Lot
▪ = Pb−Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present.

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	**WLCSP6, 2.11X1.18X0.10**	**PAGE 1 OF 1**